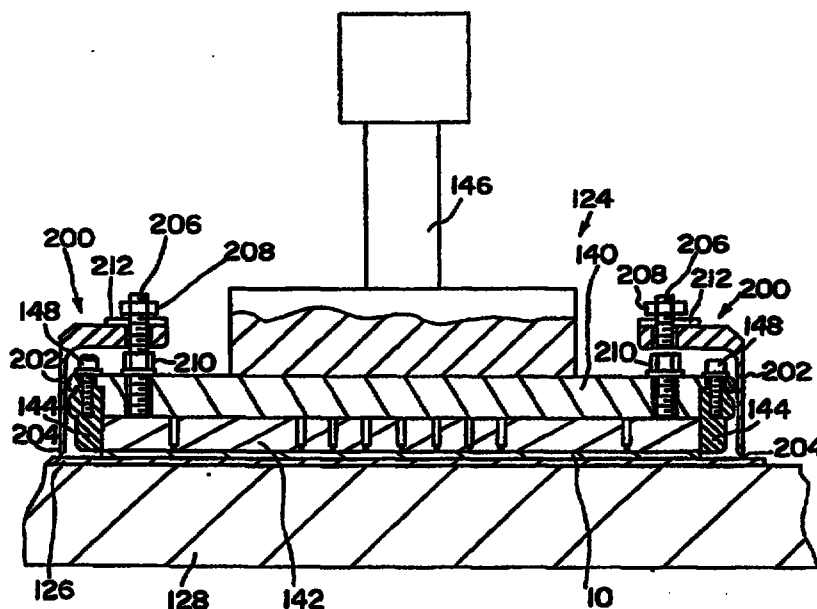




INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶ : B24B 37/04, 53/007, B24D 18/00 // H01L 21/304	A1	(11) International Publication Number: WO 99/28084 (43) International Publication Date: 10 June 1999 (10.06.99)
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(21) International Application Number: **PCT/US98/24960**(22) International Filing Date: **20 November 1998 (20.11.98)**(30) Priority Data:
08/984,243 3 December 1997 (03.12.97) US(71) Applicant: **SPEEDRAM CORPORATION [US/US]; 305 North 54th Street, Chandler, AZ 85226 (US).**(72) Inventor: **HOLZAPFEL, Paul; 4592 W. Dublin Street, Chandler, AZ 85226 (US).**(74) Agent: **ZEMAN, Laura, J.; Snell & Wilmer, One Arizona Center, 400 East Van Buren Street, Phoenix, AZ 85004-0001 (US).**(81) Designated States: **JP, KR, SG, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).****Published**
With international search report.(54) Title: **METHOD AND APPARATUS FOR CONDITIONING POLISHING PADS UTILIZING BRAZED DIAMOND TECHNOLOGY AND TITANIUM NITRIDE**

(57) Abstract

A method and apparatus for polishing and planarizing workpieces such as semiconductor wafers is presented. Conditioning rings, which are used to condition polishing pads used in the planarization or polishing of semiconductor wafers, are shown which utilize brazed diamond technology in association with a coating of a titanium nitride containing composition or a thin film diamond deposition in order to reduce the fracturing and loss of cutting elements bonded to the conditioning ring.